

## Surface Mount Termination 10 Watts, 50W



### Description

The RFP-100200A25Z50 is high performance Alumina surface mount termination intended as a lower cost alternative to Aluminum Nitride (AlN) and Beryllium Oxide (BeO). The termination is well suited to all cellular frequency bands such as; AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating 90 degree hybrid, directional couplers, and for use in isolators.

### General Specifications

<b>Resistive Element</b>	Thick film
<b>Substrate</b>	Alumina Ceramic
<b>Terminal Finish</b>	Thick film Silver
<b>Operating Temperature</b>	-55 to +125°C (see chart)

Tolerance is  $\pm 0.010$ ", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

### Electrical Specifications

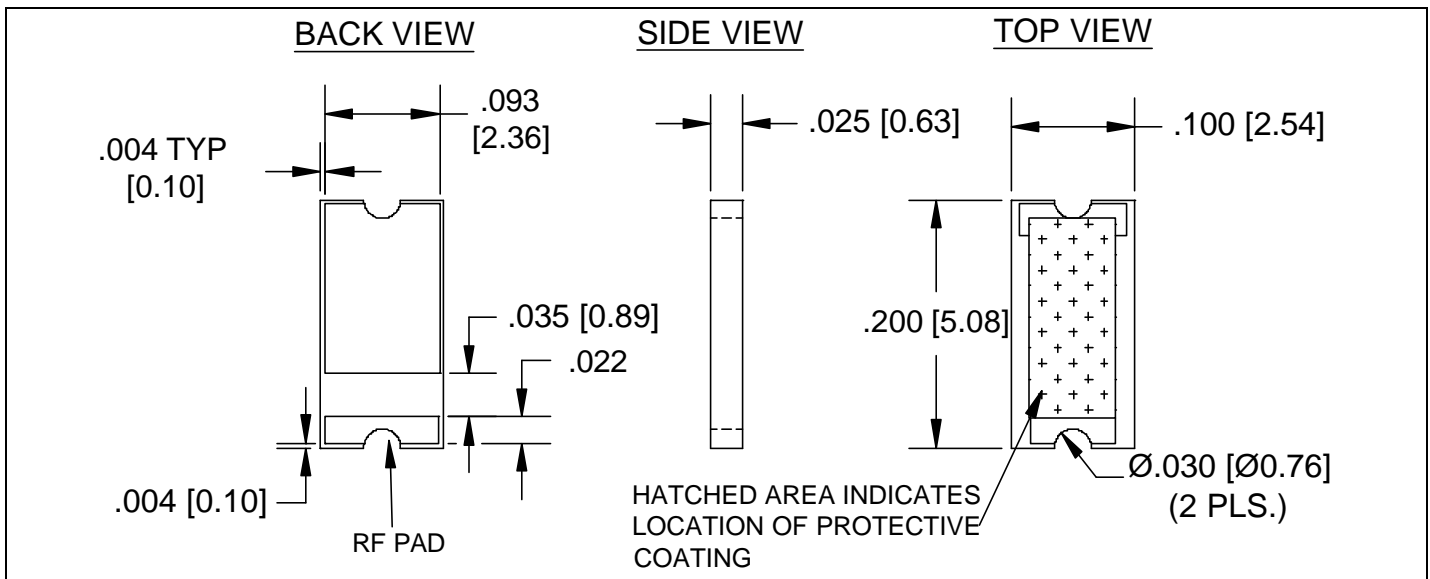
<b>Resistance Value:</b>	50 ohms, $\pm 2\%$
<b>Power:</b>	10 Watts
<b>Frequency Range:</b>	DC – 3.0 GHz
<b>V.S.W.R.:</b>	<1.25:1

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change without notice**

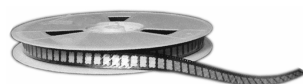
### Features:

- 10 Watts
- Lowest Cost
- True Surface Mount
- Alumina Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

### Outline Drawing

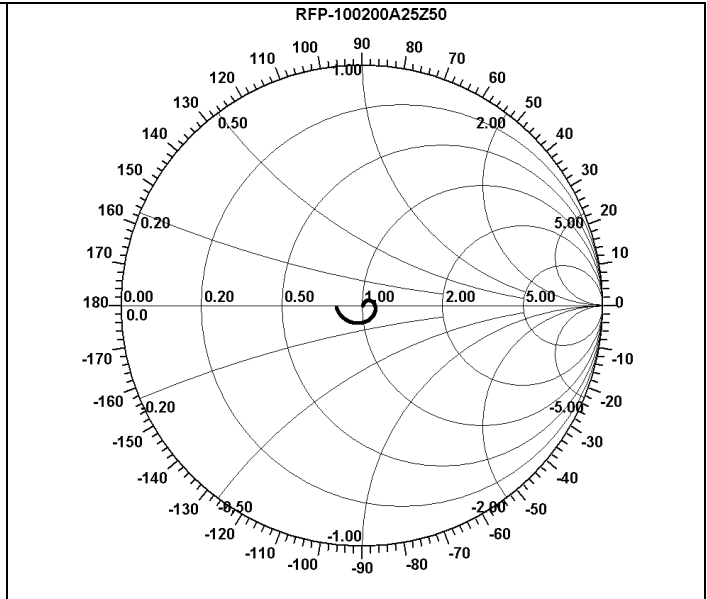
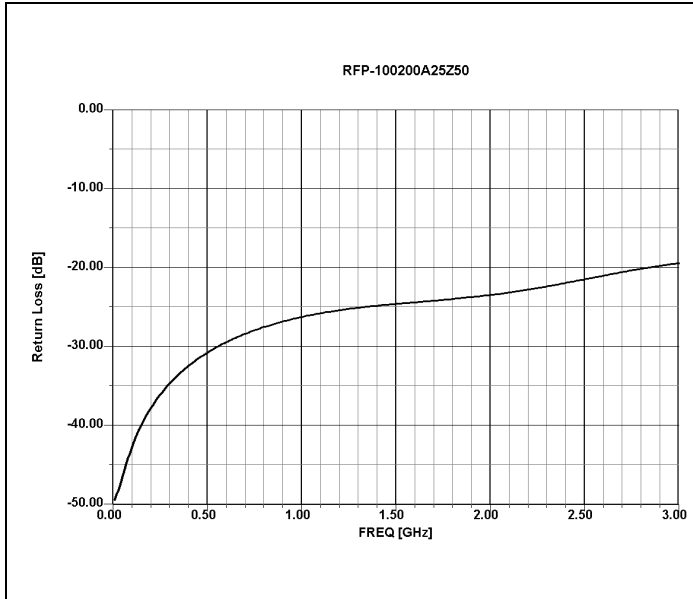


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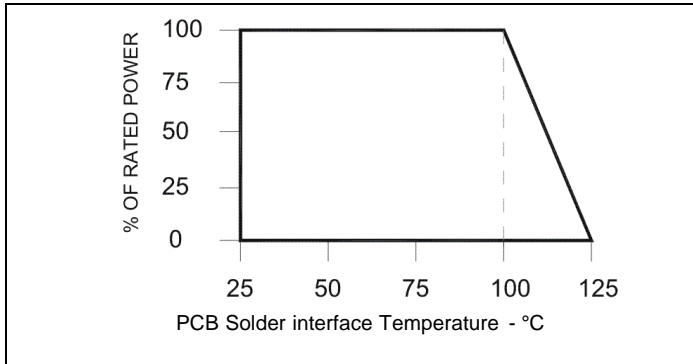




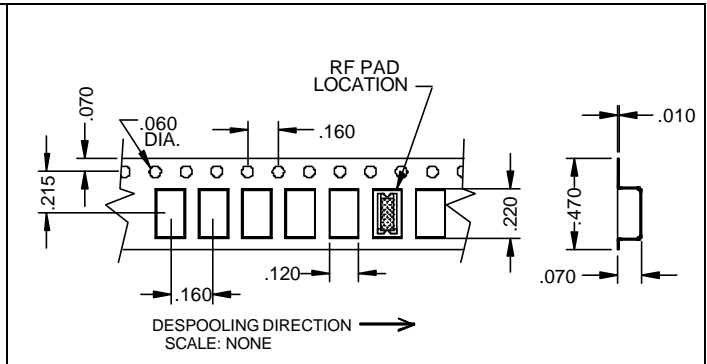
### Typical Performance:



### Power De-rating:



### Tape & Reel:



### Mounting Footprint and Procedure:

Dimension given in inches [millimeters]  
For best thermal performance the PCB should be soldered to the heat sink.

**MOUNTING PROCEDURE**

1. Drill thermal vias through PCB and fill with solder, such as SN63 type.
2. Solder part in place using SN63 type solder with controlled temperature iron (700°F).
3. To ensure good thermal connectivity to heat sink, which is critical for proper operation drill and tap heatsink and mount PCB board to heat sink using screws.

